TOSHIBA PHOTOCOUPLER

TLP759(D4)

<u>ATTACHMENT</u>: SPECIFICATIONS FOR <u>VDE0884</u> OPTION: (D4)

Types: TLP759, TLP759F

Type designations for 'Option: (D4)', which are tested under VDE0884 requirements.

Ex. : TLP759 (D4-O) D4 : VDE0884 option

O: CTR rank

Note : Use Toshiba standard type number for safety standard application.

Ex. TLP759 (D4-O) \rightarrow TLP759

VDE0884 ISOLATION CHARACTERISTICS

| DESCRIPTION | | SYMBOL | RATING | UNIT |
|---|-------------------|-------------------|----------------------|------|
| Application Classification (DIN VDE0109/12.83, Table 1) for rated mains voltage≤300 V _{RMS} for rated mains voltage≤600 V _{RMS} | | | I-IV I-III | _ |
| Climatic Classification (DIN IEC68 Teil 1/09.80) | | 55 / 100 / 21 | _ | |
| Pollution Degree (DIN VDE0109 / 12.83) | | | 2 | _ |
| Maximum Operating Insulation Voltage | TLPxxx TLPxxxF | V _{IORM} | 890 1140 | Vpk |
| Input to output Test Voltage, Method A | TLPxxx | Vpr | 1335 | Vpk |
| V_{pr} =1.5× $V_{\mbox{IORM}}$, 100% Production Test t_p =60s, Partial Discharge<5pC | TLPxxxF | | 1710 | |
| Input to output Test Voltage, Method B | TLPxxx | Vpr | 1670 | Vpk |
| $V_{pr}=1.875\times V_{\mbox{IORM}}$, 100% Production Test $t_p=1s$, Partial Discharge < 5pC | TLPxxxF | | 2140 | |
| Highest Permissible Overvoltage (Transient Overvoltage, t _{pr} =10s) | | $v_{ m TR}$ | 6000 | Vpk |
| Safety Limiting Values (Max. permissible ratings in case of fault, also refer to thermal derating curve) | | | | |
| Current (Input current IF, Psi=0) | Isi | 300 | mA | |
| Power (Output or Total Power Dissipation) | Psi | 500 | \mathbf{mW} | |
| Temperature | Tsi | 150 | $^{\circ}\mathrm{C}$ | |
| Insulation Resistance at Tsi, V _{IO} =500V | Rsi | \geq 10^9 | Ω | |

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INSULATION RELATED SPECIFICATIONS

| | | 7.62mm pitch TLP759 | 10.16mm pitch TLP759F | |
|-------------------------------|-----|-----------------------------------|--------------------------|--|
| Minimum Creepage Distance (*) | Cr | 6.4mm | 8.0mm | |
| Minimum Clearance (*) | Cl | 6.4mm | 8.0mm | |
| Minimum Insulation Thickness | ti | 0.4mm | | |
| Comperative Tracking Index | СТІ | 175 | | |
| (DIN IEC112/VDE0303, Part 1) | | (VDE0109/12.83 Group II a) | | |

- (*) in accordance with DIN VDE0109/12.83, Table 2, & 4
- 1. If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value (e. g. at a standard distance between soldering eye centres of 7.5mm). If this is not permissible, the user shall take suitable measures.
- 2. This photocoupler is suitable for 'safe electrical isolation' only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

VDE Test sign: Marking on product

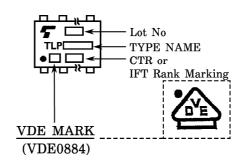
for VDE0884



Marking on packing for VDE0884



Marking Example:





Method A

(for type and sampling tests, destructive tests)

$$\begin{array}{lll} t_1,\ t_2 & = 1\ to\ 10s \\ t_3,\ t_4 & = 1s \\ t_p\ (Measuring\ time\ for\ partial\ discharge) = 60s \\ t_b & = 62s \\ t_{ini} & = 10s \end{array}$$

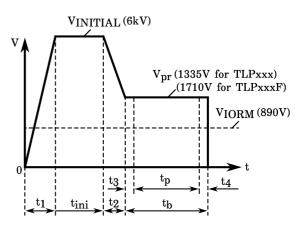


Figure 2 Partial discharge measurement procedure according to VDE0884 Non-destructive test for 100% inspection.

Method B

(for sample test, non-destructive test)

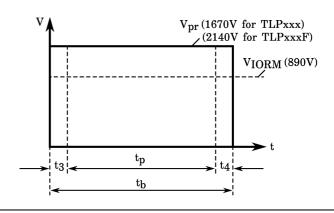
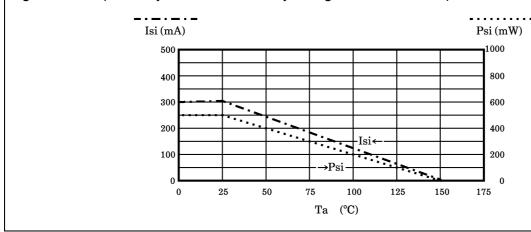


Figure 3 Dependency of maximum safety ratings on ambient temperature



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RESTRICTIONS ON PRODUCT USE

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